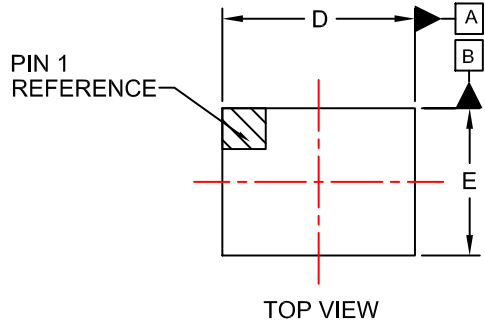




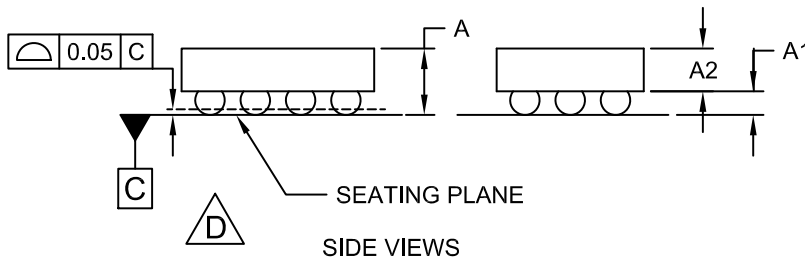
**WLCSP12 1.828x1.288x0.574**  
**CASE 567WP**  
**ISSUE O**

DATE 25 JUN 2018

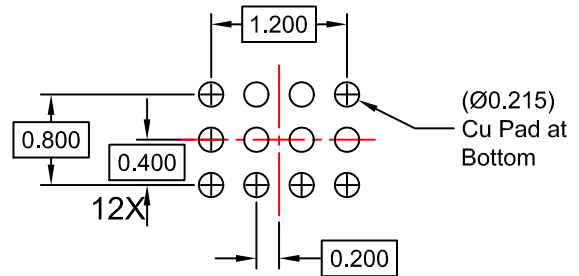
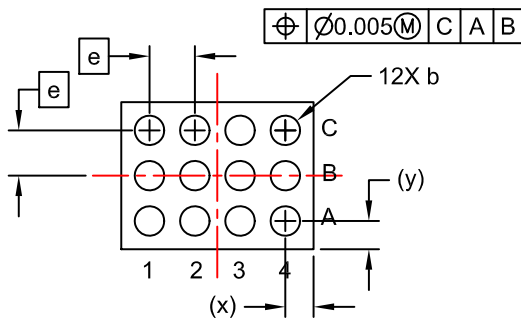


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.536	0.574	0.612
A1	0.176	0.196	0.216
A2	0.360	0.378	0.396
b	0.240	0.260	0.280
D	1.798	1.828	1.858
E	1.258	1.288	1.318
e	0.40 BSC		
x	0.299	0.314	0.329
y	0.229	0.244	0.259



RECOMMENDED  
 MOUNTING FOOTPRINT  
 (NSMD PAD TYPE)

BOTTOM VIEW

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<b>DESCRIPTION:</b>	<b>WLCSP12 1.828x1.288x0.574</b>	<b>PAGE 1 OF 1</b>

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